US00D888675S

(12) United States Design Patent
Lim

(10) **Patent No.: US D888,675 S**
(45) **Date of Patent: ** Jun. 30, 2020**

---

(54) **CASE FOR A CIRCUIT BOARD**

(71) Applicant: **SAMSUNG ELECTRONIC CO., LTD.**, Suwon-si (KR)

(72) Inventor: **Gwangman Lim**, Seoul (KR)

(73) Assignee: **SAMSUNG ELECTRONICS CO., LTD.**, Suwon-si (KR)

(**) Term: **15 Years**

(21) Appl. No.: **29/681,527**

(22) Filed: **Feb. 26, 2019**

(30) **Foreign Application Priority Data**

Aug. 29, 2018 (KR) 30-2018-0040308

(51) **LOC (12) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/184**
(58) **Field of Classification Search**
USPC D13/184, 103, 119, 162, 199, 182; D14/432, 433, 434, 435, 436
CPC H01R 13/502; H01R 13/46; H05K 5/00; H05K 7/18; H05K 7/02
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,377,080	A *	12/1994	Lin	H05K 5/0008 206/707
8,174,847	B2 *	5/2012	Ohtsuji	H05K 9/005 361/818
8,269,116	B2 *	9/2012	Ambo	H05K 5/0069 174/541
8,503,191	B2 *	8/2013	Nagata	H01R 13/6658 361/818
8,981,240	B2 *	3/2015	Chitaka	H05K 5/061 174/50
D760,176	S	6/2016	Greiser	
D760,186	S	6/2016	Geiser	
9,526,186	B2 *	12/2016	Lin	H05K 5/0278
D827,594	S *	9/2018	Shim	D13/184
D828,358	S *	9/2018	Lim	D14/436
D834,025	S *	11/2018	Lim	D14/436
D847,813	S *	5/2019	Jun	D14/356
D848,418	S *	5/2019	Jun	D14/356
D848,419	S *	5/2019	Jun	D14/356
D866,558	S *	11/2019	Shim	D14/435
2008/0096413	A1 *	4/2008	Chen	H01R 13/2442 439/345
2014/0256164	A1 *	9/2014	Lin	G06K 19/07732 439/76.1

OTHER PUBLICATIONS

Communication dated Nov. 26, 2019, from the Japanese Patent Office in counterpart application No. 2019-004032.

* cited by examiner

Primary Examiner — Janice Hallmark
Assistant Examiner — Harold E Blackwell, II
(74) *Attorney, Agent, or Firm* — Sughrue Mion, PLLC

(57) CLAIM

The ornamental design for a case for a circuit board, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a case for a circuit board showing our new design.
FIG. **2** is a front elevation view thereof.
FIG. **3** is a rear elevation view thereof.
FIG. **4** is a left side elevation view thereof.
FIG. **5** is a right side elevation view thereof.
FIG. **6** is a top plan view thereof.
FIG. **7** is a bottom plan view thereof; and,
FIG. **8** is a perspective view of a case for a circuit board shown in an example environment.
The broken lines are for environmental purposes only and form no part of the claimed design.

1 Claim, 6 Drawing Sheets

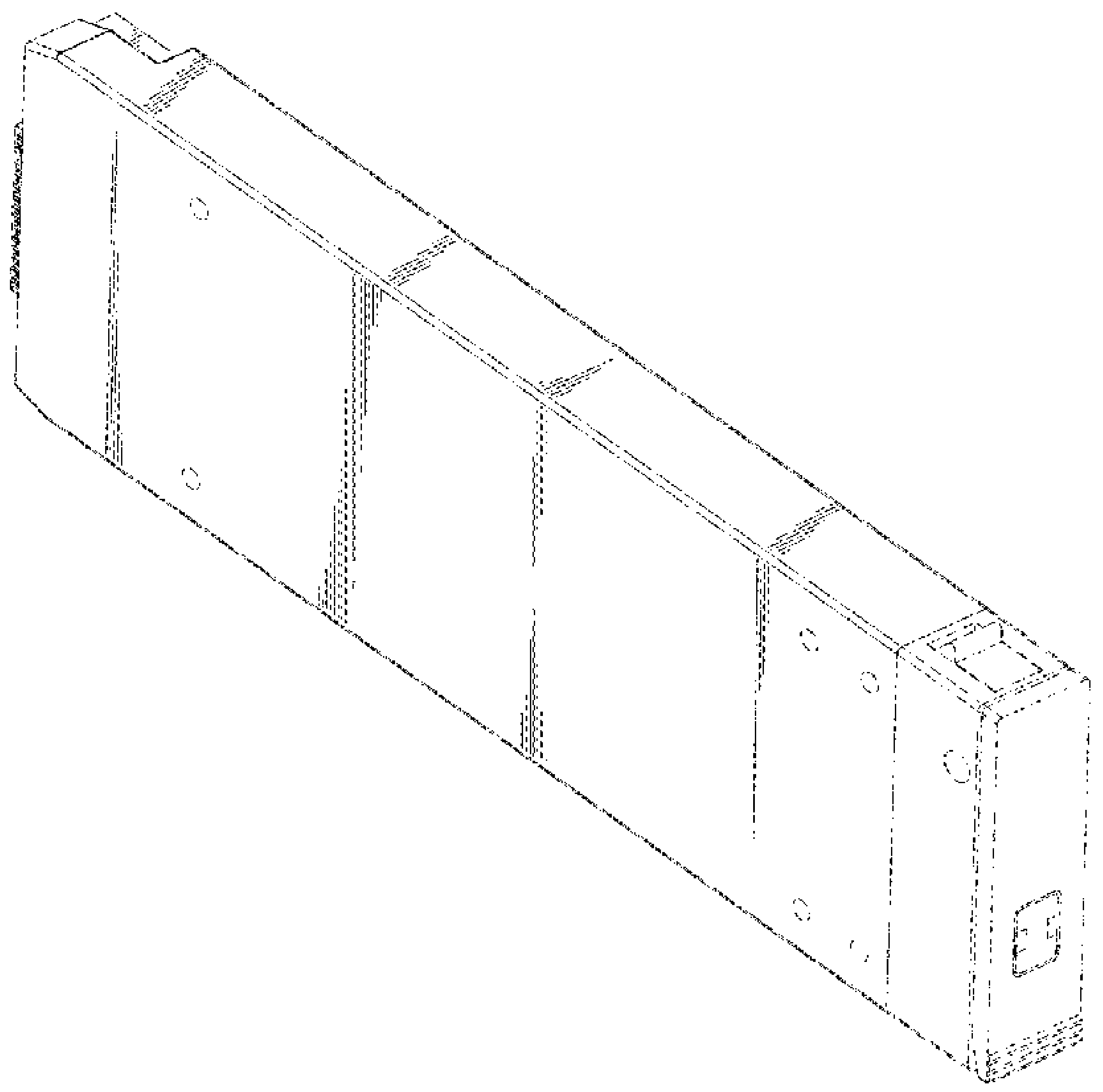

FIG. 1

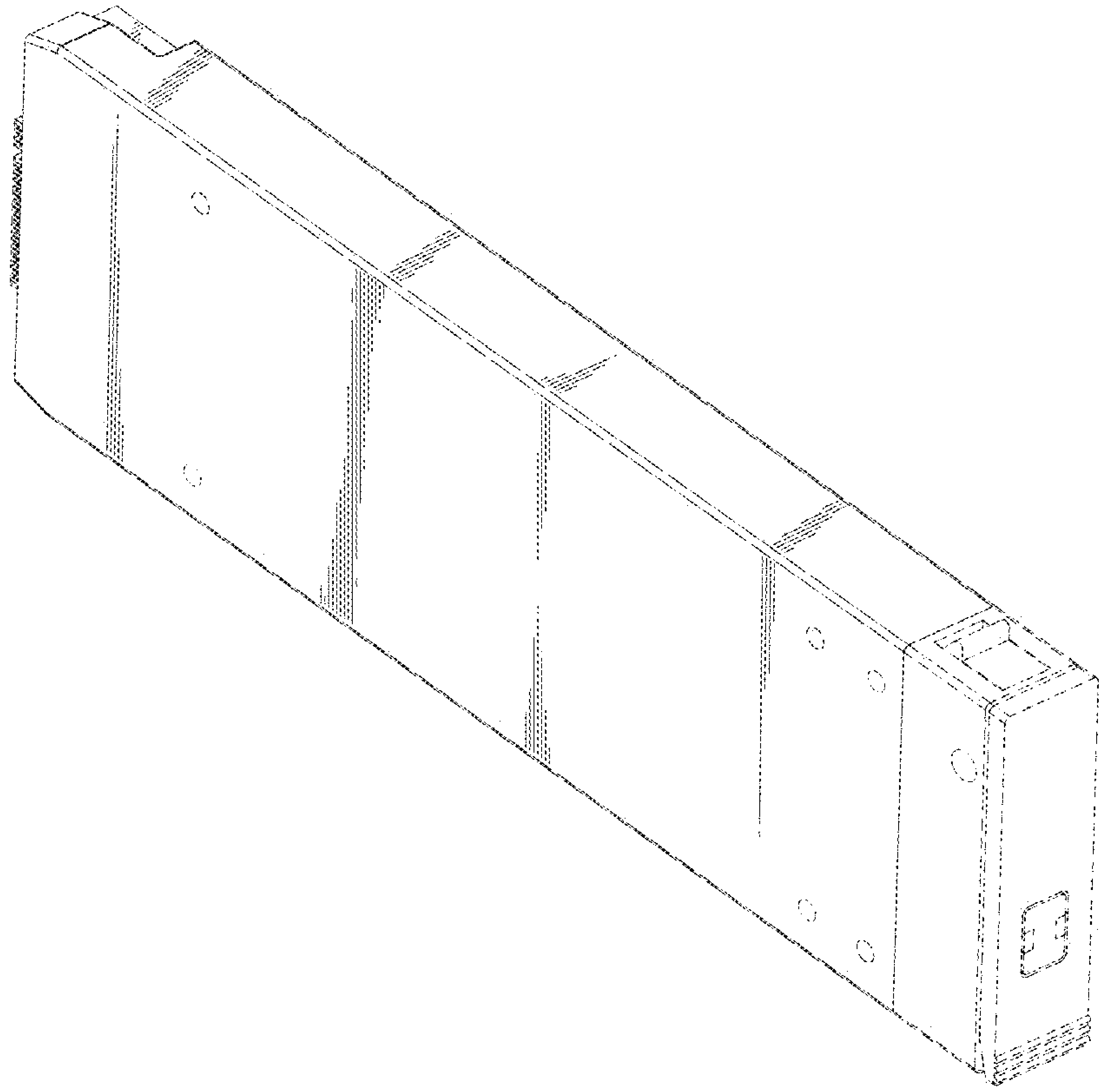

FIG. 2

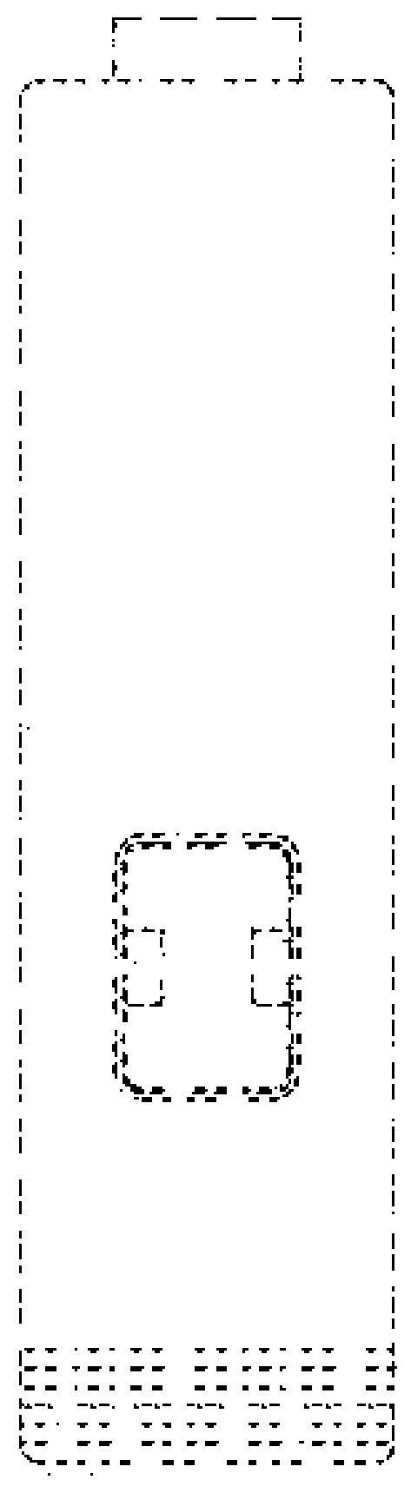

FIG. 3

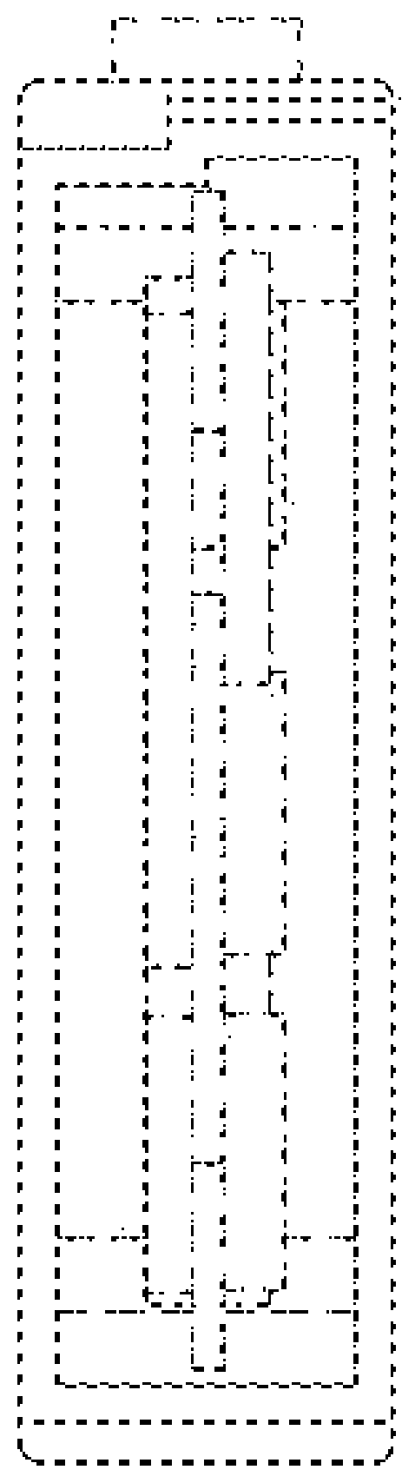

FIG. 4

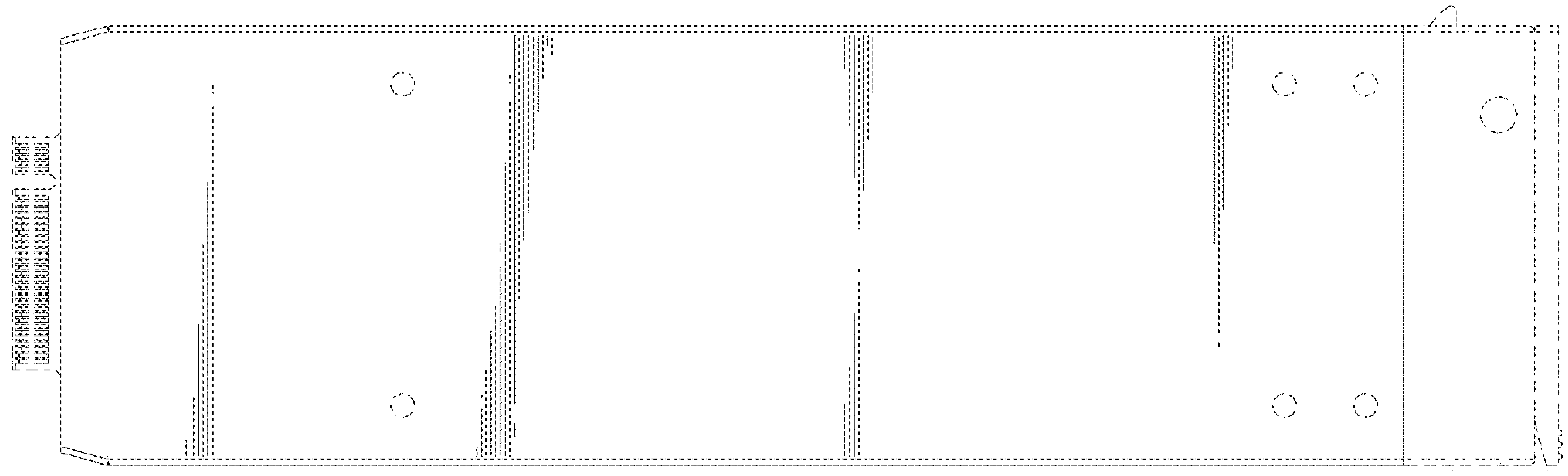

FIG. 5

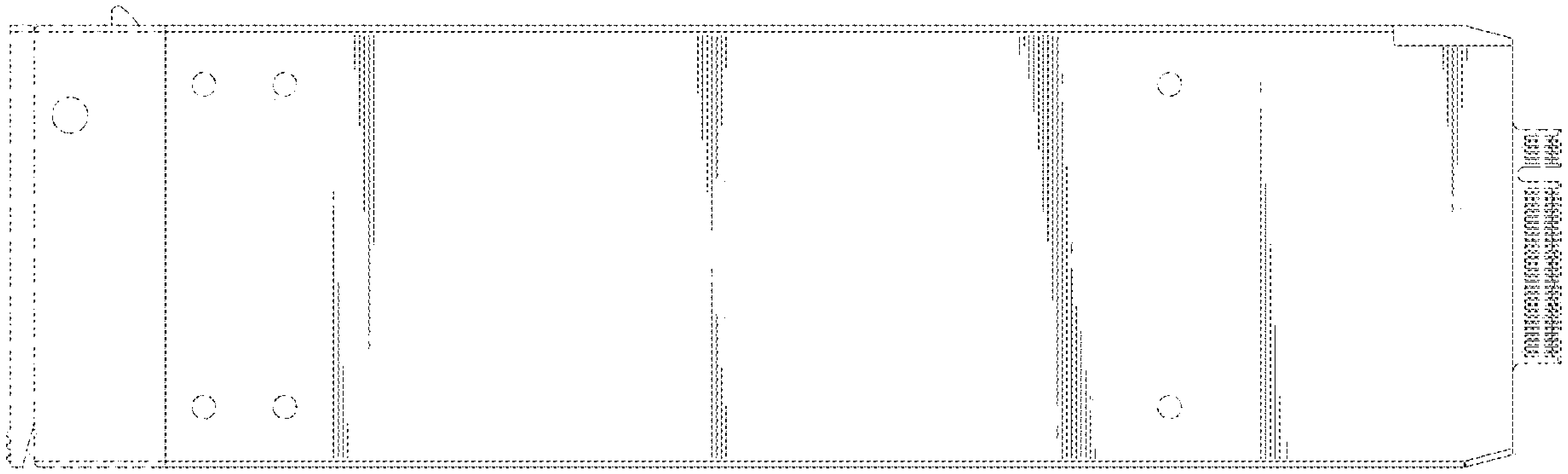

FIG. 6

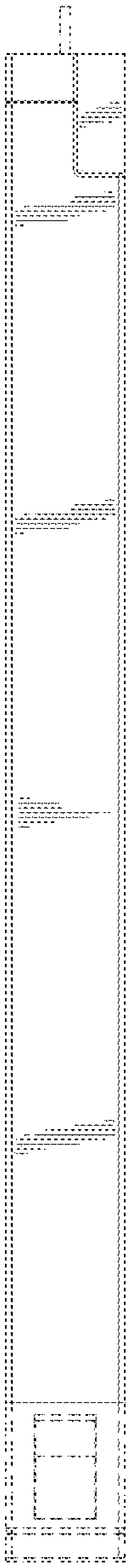

FIG. 7

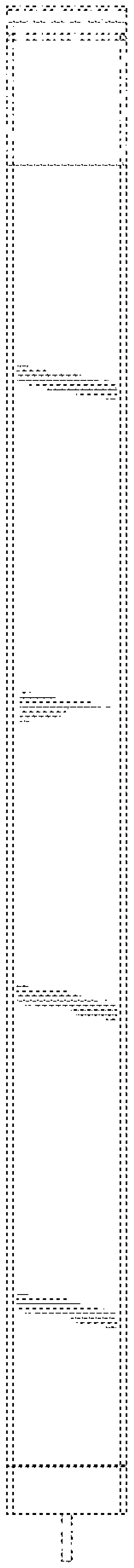

FIG. 8